# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4836716

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| **SUBMISSION TYPE:** | NEW ASSIGNMENT |
| **NATURE OF CONVEYANCE:** | ASSIGNMENT |

**CONVEYING PARTY DATA**

| Name | Execution Date |
|---|---|
| Chih-Kai Hsu | 01/30/2018 |
| Ssu-I Fu | 01/31/2018 |
| Chun-Ya Chiu | 01/31/2018 |
| Chi-Ting Wu | 01/31/2018 |
| Chin-Hung Chen | 01/31/2018 |
| Yu-Hsiang Lin | 01/31/2018 |

**RECEIVING PARTY DATA**

| | |
|---|---|
| **Name:** | UNITED MICROELECTRONICS CORP. |
| **Street Address:** | No.3, Li-Hsin Road 2, Science-Based Industrial Park |
| **City:** | Hsin-Chu City |
| **State/Country:** | TAIWAN |

**PROPERTY NUMBERS Total: 1**

| Property Type | Number |
|---|---|
| **Application Number:** | 15873838 |

**CORRESPONDENCE DATA**

**Fax Number:** (703)997-4517

***Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***

**Phone:** 3027291562
**Email:** Patent.admin.uspto.cr@naipo.com
**Correspondent Name:** WINSTON HSU
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**Address Line 4:** NEW TAIPEI CITY, TAIWAN

| | |
|---|---|
| **ATTORNEY DOCKET NUMBER:** | NAUP3226USA |
| **NAME OF SUBMITTER:** | SIBYL YU |
| **SIGNATURE:** | /SIBYL YU/ |
| **DATE SIGNED:** | 02/22/2018 |

**Total Attachments: 12**
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Docket No NAUP3226USA

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

**Title of Invention:**
**SEMICONDUCTOR DEVICE AND METHOD FOR FABRICATING THE SAME**

As the below named inventor, I hereby declare that:
This declaration is directed to:

☐ The attached application, or

☑ United States application number 15/873,838 filed on 01/17/2018 , or

☐ PCT international application number ________ filed on ________

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of **No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.**

(referred to as "ASSIGNEE"below) to I of the sum of One Dollar ($ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.
IN WITNESS WHEREOF, I have hereunto set hand and seal this JAN 3 0 2018 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chih-Kai Hsu** Date: JAN 30 2018

Signature: Chih-Kai Hsu

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Docket No NAUP3226USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ssu-I Fu** Date: JAN 31 2018

Signature: Ssu-I Fu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chun-Ya Chiu** Date: JAN 3 1 2018

Signature: Chun-Ya Chiu

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chi-Ting Wu**

Date: JAN 31 2018

Signature: Chi-Ting Wu.

Docket No NAUP3226USA

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chin-Hung Chen** Date: JAN 31 2018

Signature: Chin-Hung Chen

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yu-Hsiang Lin** Date: JAN 31 2018

Signature: 林鈺翔 Yu-Hsiang Lin